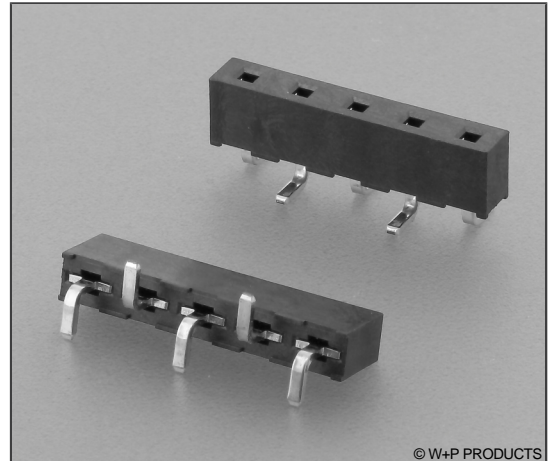


SMT-Buchsenleisten RM 5,08mm, stehend – Power-Kontakte SMT Female Headers, 5.08mm Pitch, Vertical – Power Contacts

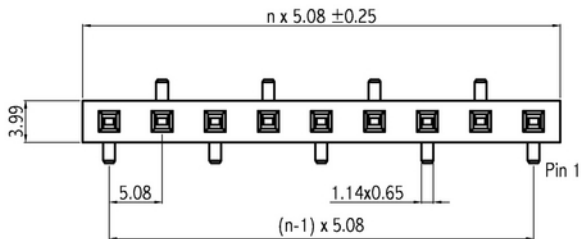
Technische Daten / Technical Data

Isolierkörper <i>Insulator</i>	Thermoplastischer Kunststoff, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i>
Kontaktmaterial <i>Contact Material</i>	Kupferlegierung <i>Copper alloy</i>
Kontaktoberfläche <i>Contact Surface</i>	Lt. Oberflächenoptionen, über Ni (1,3 ... 2,5µm) <i>Acc. to options (see below), over Ni (1.3 ... 2.5µm)</i>
Lötbarkeit <i>Solderability</i>	IEC 60512-12A <i>IEC 60512-12A</i>
Durchgangswiderstand <i>Contact Resistance</i>	< 10mΩ <i>< 10mΩ</i>
Isolationswiderstand <i>Insulation Resistance</i>	> 500MΩ <i>> 500MΩ</i>
Spannungsfestigkeit <i>Test Voltage</i>	500V _{AC} <i>500V_{AC}</i>
Nennstrom <i>Current Rating</i>	6,8A <i>6.8A</i>
Temperaturbereich <i>Temperature Range</i>	-40°C ... +125°C <i>-40°C ... +125°C</i>
Verarbeitung <i>Processing</i>	Reflow-Lötverfahren <i>Reflow soldering</i>

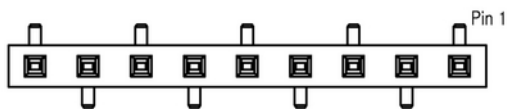


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Passende Stiftleisten:
Compatible Pin Headers:
9850 9860 985 986

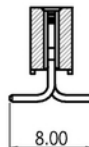
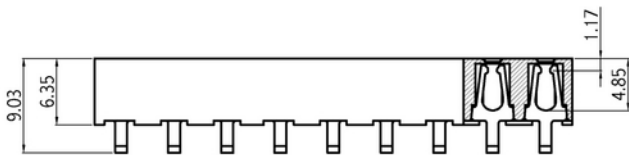
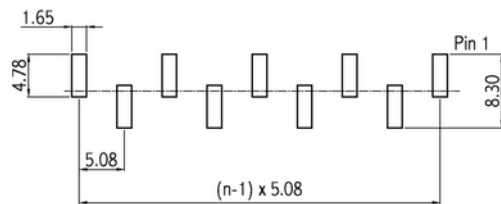
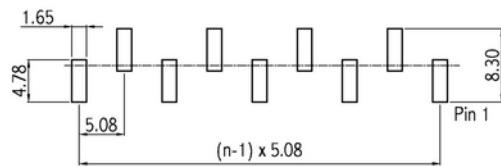


Layout B1



Layout B2

PCB Layouts



Series	Contacts*	Type*	Plating*	Packaging*
3960	05 02-20	1 1 Layout B1 2 Layout B2	00 00 Vergoldet Gold plated 50 Verzinkt Tin plated 60 Sel. Au/Sn Duplex plating	ST ST PPST PPTR

* Dies ist ein **Bestellbeispiel** - bitte durch Ihre Spezifikationen ersetzen.
* This is an **order example** - please replace by your specifications.

Lieferformen / Packaging Options:

- ST** In Stangen / In tubes
- PPST** In Stangen mit Pick&Place-Pads / In tubes with Pick&Place-Pads
- PPTR** Tape & Reel mit P&P-Pads / Tape & Reel with P&P-Pads

Informationen zum Reflow-Lötverfahren

Reflow Soldering Information

Reflow-Lötempfehlung

Reflow Soldering Recommendation

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150°C
Temperatur Maximum T_{Smax}	200°C
Dauer $T_{Smin} - T_{Smax}$	60-180s
Temperatur Lötbereich T_L	217°C
Verweildauer oberhalb T_L	60-180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3°C / s
Höchsttemperatur T_P	260°C ±5
Dauer Höchsttemperatur	20-40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6°C / s
Dauer 25°C - Höchsttemperatur T_P	Max. 8 min

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150°C
Maximum Temperatur T_{Smax}	200°C
Duration $T_{Smin} - T_{Smax}$	60-180s
Soldering Range Temperature T_L	217°C
Duration above T_L	60-180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3°C / s
Peak Temperature T_P	260°C ±5
Duration Peak Temperature	20-40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6°C / s
Duration 25°C - Peak Temp. T_P	Max. 8min

